

# ESDAVLC6V1-1BM2, ESDAVLC6V1-1BT2

## Single line low capacitance Transil™ for ESD protection

### **Features**

- Single line bi-directional protection
- Breakdown voltage V<sub>BR</sub> = 6.1 V min.
- Very low capacitance (6 pF typ. @ 3 V)
- Lead-free package

#### **Benefits**

- Very low capacitance for optimized data integrity
- Very low reverse current < 0.1 µA
- Low PCB space consumption: 0.6 mm<sup>2</sup> max
- High reliability offered by monolithic integration

### Complies with the following standards:

- IEC 61000-4-2 level 4
  - 15 kV (air discharge)
  - 8 kV (contact discharge)
- MIL STD 883G Method 3015-7: class 3 B
  - Human body model

## **Applications**

Where transient overvoltage protection in ESD sensitive equipment is required, such as:

- Computers
- Printers
- Communication systems
- Cellular phone handsets and accessories
- Video equipment

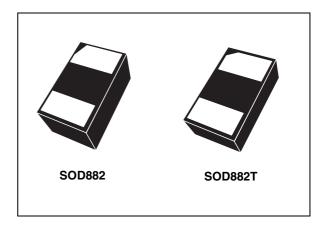
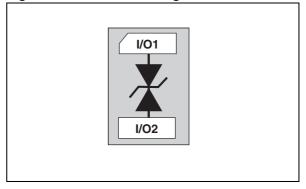


Figure 1. Functional diagram



### **Description**

The ESDAVLC6V1-1BM2 and ESDAVLC6V1-1BT2 are monolithic application specific devices dedicated to ESD protection of high speed serial interfaces such as USB 2.0, display and camera interface.

The devices are ideal for applications where both printed circuit board space and power absorption capability are required.

TM: Transil is a trademark of STMicroelectronics

## 1 Characteristics

Table 1. Absolute maximum ratings ( $T_{amb} = 25^{\circ} C$ )

Symbol		Value	Unit		
		IEC 61000-4-2 contact of	lischarge	15	
V <sub>PP</sub> <sup>(1)</sup>	Peak pulse voltage	IEC 61000-4-2 air discharge		15	kV
		MIL STD 883G - Method 3015-7: class 3B		25	
P <sub>PP</sub> <sup>(1)</sup>	Peak pulse power dissipation (8/20 $\mu$ s) $T_j$ initial = $T_{amb}$			30	W
I <sub>PP</sub>	Peak pulse current (8/20 μs)			2.5	Α
T <sub>j</sub>	Junction temperature			125	°C
T <sub>stg</sub>	Storage temperature range			- 55 to + 150	°C
$T_L$	Maximum lead temperature for soldering during 10 s			260	ç
T <sub>OP</sub>	Operating temperature range			- 40 to + 125	°C

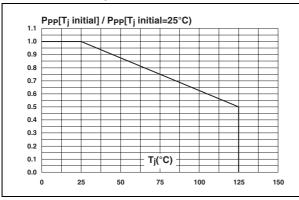
<sup>1.</sup> For a surge greater than the maximum values, the diode will fail in short-circuit.

Table 2. Electrical characteristics ( $T_{amb} = 25^{\circ} C$ )

Symbol	Parameter			1	1
V <sub>RM</sub>	Stand-of voltage				
V <sub>BR</sub>	Breakdown voltage				
V <sub>CL</sub>	Clamping voltage		V <sub>BR</sub> V <sub>RM</sub> I	I <sub>R</sub>	V V <sub>BR</sub>
I <sub>RM</sub>	Leakage current @ V <sub>RM</sub>		·····	I <sub>R</sub>	· Bh
I <sub>PP</sub>	Peak pulse current				
Parameter	Test condition	Min	Тур	Max	Unit
$V_{BR}$	I <sub>R</sub> = 1 mA	6.1			V
I <sub>RM</sub>	V <sub>RM</sub> = 3 V			100	nA
R <sub>d</sub>			1.6		Ω
				0.5	10 <sup>-4</sup> /°C
αΤ				2.5	10 / 0
αT C	F = 1 MHz, V <sub>R</sub> = 0 V		7	2.5 8	pF

Figure 2. Relative variation of peak pulse power versus initial junction temperature

Figure 3. Peak pulse power versus exponential pulse duration



1000 Ppp(W)

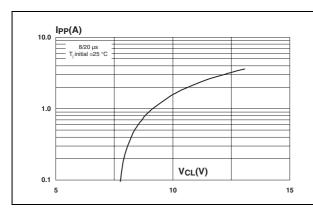
1000 tpp(W)

100 tpp(Ms)

10 100 100

Figure 4. Clamping voltage versus peak pulse current (typical values)

Figure 5. Junction capacitance versus reverse voltage applied (typical values)



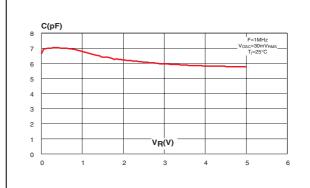
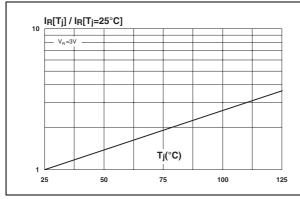


Figure 6. Relative variation of leakage current versus junction temperature (typical values)

Figure 7. S21 attenuation measurement result



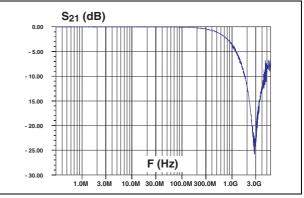


Figure 8. ESD response to IEC 61000-4-2 (+2 kV air discharge)

Figure 9. ESD response to IEC 61000-4-2 (-2 kV air discharge)

Figure 10. ESD response to IEC 61000-4-2 (+8 kV air discharge)

Figure 11. ESD response to IEC 61000-4-2 (-8 kV air discharge)

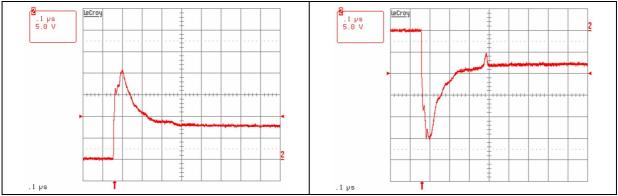
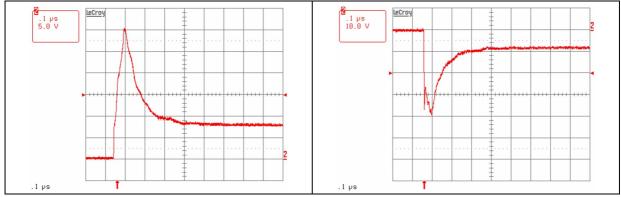


Figure 12. ESD response to IEC 61000-4-2 (+15 kV air discharge)

Figure 13. ESD response to IEC 61000-4-2 (-15 kV air discharge)



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Figure 14. ESD response to IEC 61000-4-2 (+2 kV contact discharge)

Figure 15. ESD response to IEC 61000-4-2 (-2 kV contact discharge)

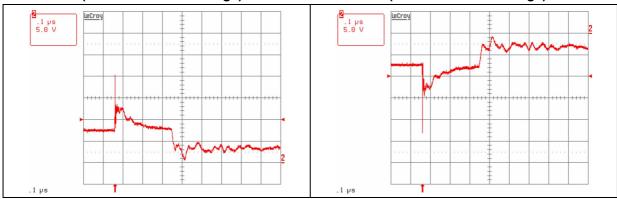


Figure 16. ESD response to IEC 61000-4-2 (+8 kV contact discharge)

Figure 17. ESD response to IEC 61000-4-2 (-8 kV contact discharge)

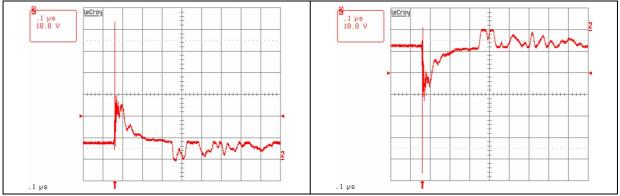
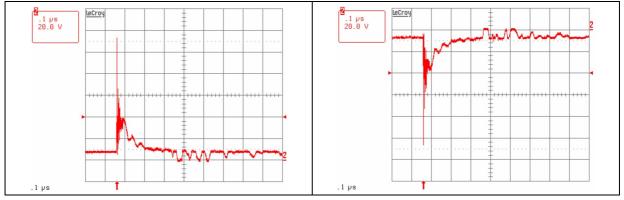


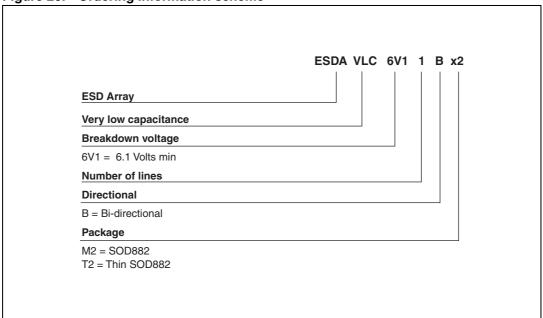
Figure 18. ESD response to IEC 61000-4-2 (+15 kV contact discharge)

Figure 19. ESD response to IEC 61000-4-2 (-15kV contact discharge)



# 2 Ordering information scheme

Figure 20. Ordering information scheme



## 3 Package information

### Epoxy meets UL94, V0

In order to meet environmental requirements, ST offers these devices in ECOPACK<sup>®</sup> packages. These packages have a lead-free second level interconnect. The category of second level interconnect is marked on the inner box label, in compliance with JEDEC Standard JESD97. The maximum ratings related to soldering conditions are also marked on the inner box label. ECOPACK is an ST trademark. ECOPACK specifications are available at <a href="https://www.st.com">www.st.com</a>.

Table 3. SOD882 dimensions

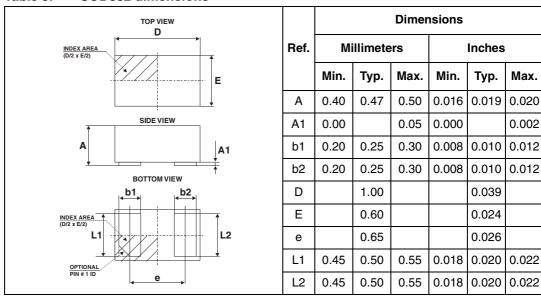
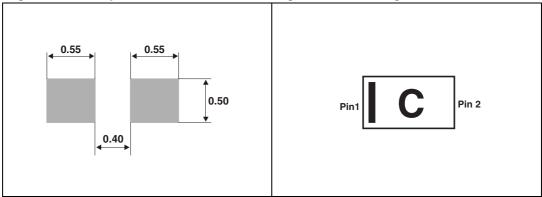


Figure 21. Footprint

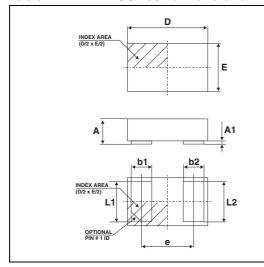
Figure 22. Marking



Note:

Product marking may be rotated by 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

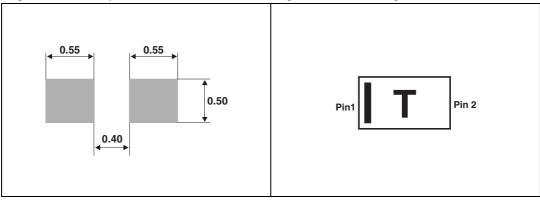
Table 4. Thin SOD882 dimensions



	Dimensions						
Ref.	Mi	illimete	ers Inches			i	
	Min.	Тур.	Max.	Min.	Тур.	Max.	
Α	0.30		0.40	0.012		0.016	
A1	0.00		0.05	0.000		0.002	
b1	0.20	0.25	0.30	0.008	0.010	0.012	
b2	0.20	0.25	0.30	0.008	0.010	0.012	
D		1.00			0.039		
Е		0.60			0.024		
е		0.65			0.026		
L1	0.45	0.50	0.55	0.018	0.020	0.022	
L2	0.45	0.50	0.55	0.018	0.020	0.022	

Figure 23. Footprint

Figure 24. Marking



Note:

Product marking may be rotated by 90° for assembly plant differentiation. In no case should this product marking be used to orient the component for its placement on a PCB. Only pin 1 mark is to be used for this purpose.

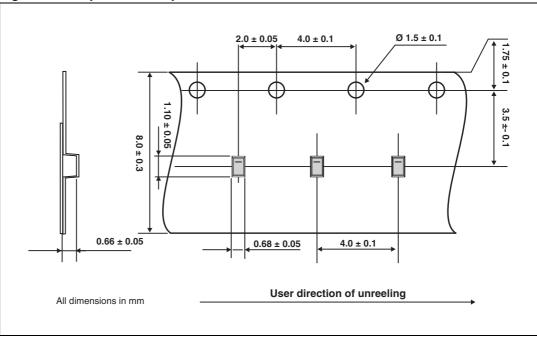


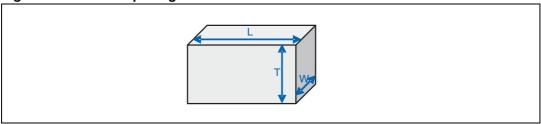
Figure 25. Tape and reel specifications

## 4 Recommendation on PCB assembly

### 4.1 Stencil opening design

- 1. General recommendation on stencil opening design
  - a) Stencil opening dimensions: L (Length), W (Width), T (Thickness).

Figure 26. Stencil opening dimensions



b) General design rule

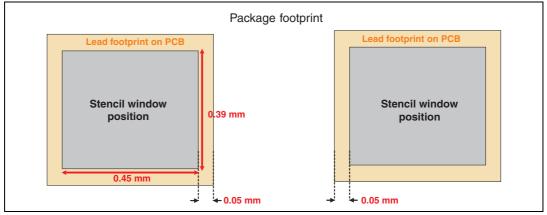
Stencil thickness (T) = 75  $\sim$  125  $\mu m$ 

Aspect Ratio = 
$$\frac{W}{T} \ge 1.5$$

Aspect Area = 
$$\frac{L \times W}{2T(L+W)} \ge 0.66$$

- 2. Reference design
  - a) Stencil opening thickness: 100 μm
  - b) Stencil opening for leads: Opening to footprint ratio between 60% and 65%.

Figure 27. Recommended stencil windows position



### 4.2 Solder paste

- 1. Halide-free flux qualification ROL0 according to ANSI/J-STD-004.
- 2. "No clean" solder paste is recommended.
- 3. Offers a high tack force to resist component movement during high speed
- 4. Solder paste with fine particles: powder particle size is 20-45 μm.

#### 4.3 **Placement**

- Manual positioning is not recommended.
- 2. It is recommended to use the lead recognition capabilities of the placement system, not the outline centering
- Standard tolerance of + 0.05 mm is recommended. 3.
- 3.5 N placement force is recommended. Too much placement force can lead to squeezed out solder paste and cause solder joints to short. Too low placement force can lead to insufficient contact between package and solder paste that could cause open solder joints or badly centered packages.
- To improve the package placement accuracy, a bottom side optical control should be performed with a high resolution tool.
- For assembly, a perfect supporting of the PCB (all the more on flexible PCB) is recommended during solder paste printing, pick and place and reflow soldering by using optimized tools.

#### 4.4 PCB design preference

- To control the solder paste amount, the closed via is recommended instead of open
- The position of tracks and open vias in the solder area should be well balanced. The symmetrical layout is recommended, in case any tilt phenomena caused by asymmetrical solder paste amount due to the solder flow away.

#### 4.5 Reflow profile

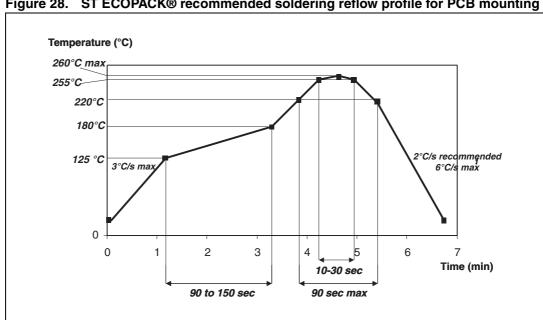


Figure 28. ST ECOPACK® recommended soldering reflow profile for PCB mounting

Note: Minimize air convection currents in the reflow oven to avoid component movement.

# 5 Ordering information

Table 5. Ordering information

Order code	Marking	Package	Weight	Base qty	Delivery mode
ESDAVLC6V1-1BM2	C <sup>(1)</sup>	SOD882	0.92 mg	3000	Tape and reel
ESDAVLC6V1-1BT2	T <sup>(1)</sup>	SOD882 Thin	0.76 mg	3000	Tape and reel

<sup>1.</sup> The marking can be rotated by  $90^{\circ}$  to differentiate assembly location

# 6 Revision history

Table 6. Document revision history

Date	Revision	Changes
16-Apr-2008	1	Initial release.

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